



## [ThC1] Advanced Metrology & inspection, Process diagnostics & control, and Yield management V

<b>Session Date</b>	November 13 (Thu.), 2025
<b>Session Time</b>	09:00-10:20
<b>Session Room</b>	Room C (Grand Ballroom 3, 2F)
<b>Session Chair</b>	Dr. Dae-Woong Kim (KIMM, Korea)

**[ThC1-1] [Invited] 09:00-09:20**

### High-/Low-Pressure Swing Annealing for Uniform Curing of High-Aspect-Ratio TiN Electrodes in DRAM Capacitors

Won Jun Jang (Sungkyunkwan Univ. and Wonik IPS, Korea), Won Sik Ahn (Wonik IPS, Korea), Woo Hui Lee, and Hyoungsub Kim (Sungkyunkwan Univ., Korea)

**[ThC1-2] [Invited] 09:20-09:50**

### A New Approach to High-Throughput Defect Review of Unpatterned Wafers for Leading Edge Nodes

Ali Ozhan Altun (UNISERS AG, Switzerland)

**[ThC1-3] [Invited] 09:50-10:20**

### Advanced Technique for Analysis of Defect States in Future 3D Semiconductor Devices

Hagyoul Bae (Jeonbuk Nat'l Univ., Korea)